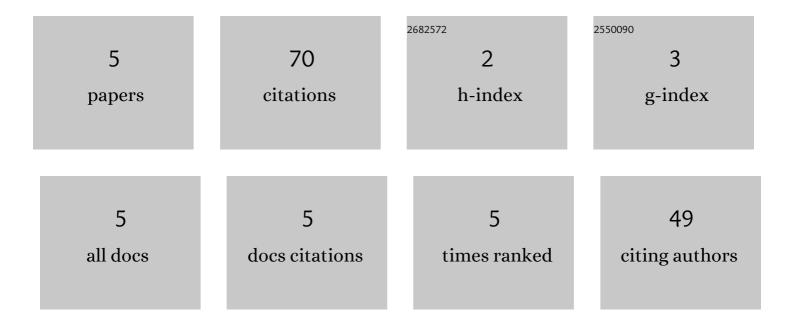
Andreas Larsson

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/3193160/publications.pdf Version: 2024-02-01



#	Article	IF	CITATIONS
1	Au-Sn SLID Bonding: A Reliable HT Interconnect and Die Attach Technology. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2013, 44, 406-413.	2.1	35
2	Effect of Temperature on the Die Shear Strength of a Au-Sn SLID Bond. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 2914-2916.	2.2	23
3	Intermetallic Bonding for High-Temperature Microelectronics and Microsystems: Solid-Liquid Interdiffusion Bonding. , 0, , .		9
4	Off-Eutectic Au–Ge Die-Attach—Microstructure, Mechanical Strength, and Electrical Resistivity. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2465-2475.	2.5	2
5	Partially Liquid Interconnects With The Au–Ge System – Mechanical Strength and Electrical Resistivity. , 2019, , .		1